

# NCP81231

## High Resolution Buck Controller with Full USB PD Features and 100% Duty Operation

The NCP81231 is a synchronous buck that is optimized for converting battery voltage or adaptor voltage into power supply rails required in notebook, tablet, and desktop systems, as well as many other consumer devices using USB PD standard and C-Type cables. The NCP81231 is fully compliant to the USB Power Delivery Specification when used in conjunction with a USB PD or C-Type Interface Controller. NCP81231 is designed for applications requiring dynamically controlled slew rate limited output voltage.

### Features

- Wide Input Voltage Range: from 4.5 V to 28 V
- Dynamically Programmed Frequency from 150 kHz to 1.2 MHz
- I<sup>2</sup>C Interface
- Real Time Power Good Indication
- Controlled Slew Rate Voltage Transitioning
- Feedback Pin with Internally Programmed Reference
- High Resolution DAC Voltage
- Two Independent Current Sensing Inputs
- Support Inductor DCR Sensing
- Over Temperature Protection
- Adaptive Non-Overlap Gate Drivers
- Filter Capacitor Switch Control
- 100% Duty Cycle Operation
- Latched Over-Voltage and Over-Current Protection
- Dead Battery Power Support
- 5 x 5 mm QFN32 Package

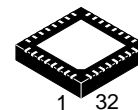
### Typical Application

- Notebooks, Tablets, Desktops
- Gaming
- Monitors, TVs, and Set Top Boxes
- Consumer Electronics
- Car Chargers
- Docking Stations
- Power Banks



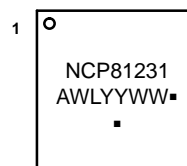
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QFN32 5x5, 0.5P  
CASE 485CE

### MARKING DIAGRAM



A = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

| Device        | Package            | Shipping†             |
|---------------|--------------------|-----------------------|
| NCP81231MNTXG | QFN32<br>(Pb-Free) | 4000 / Tape<br>& Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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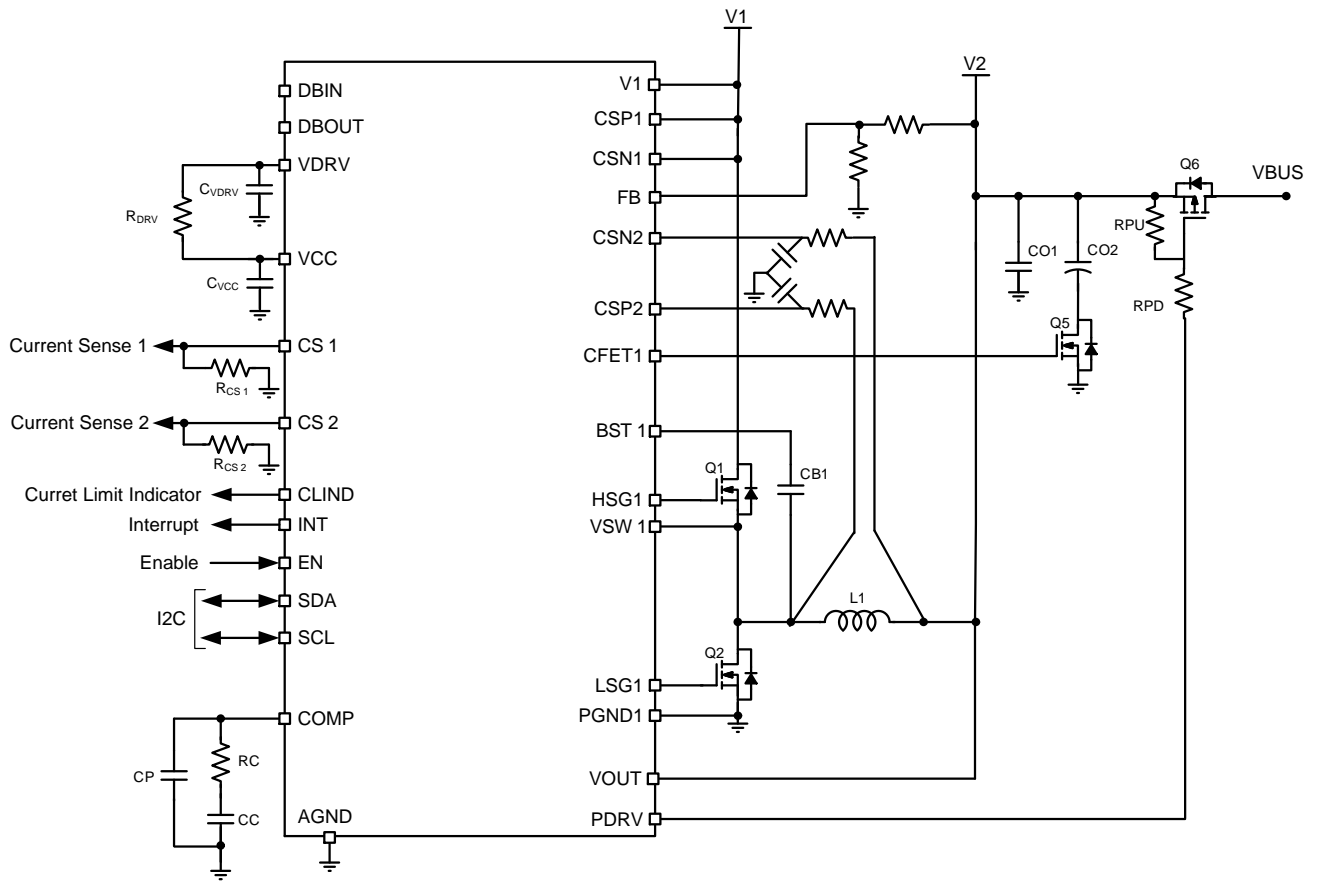


Figure 1. Typical Application Circuit (DCR)

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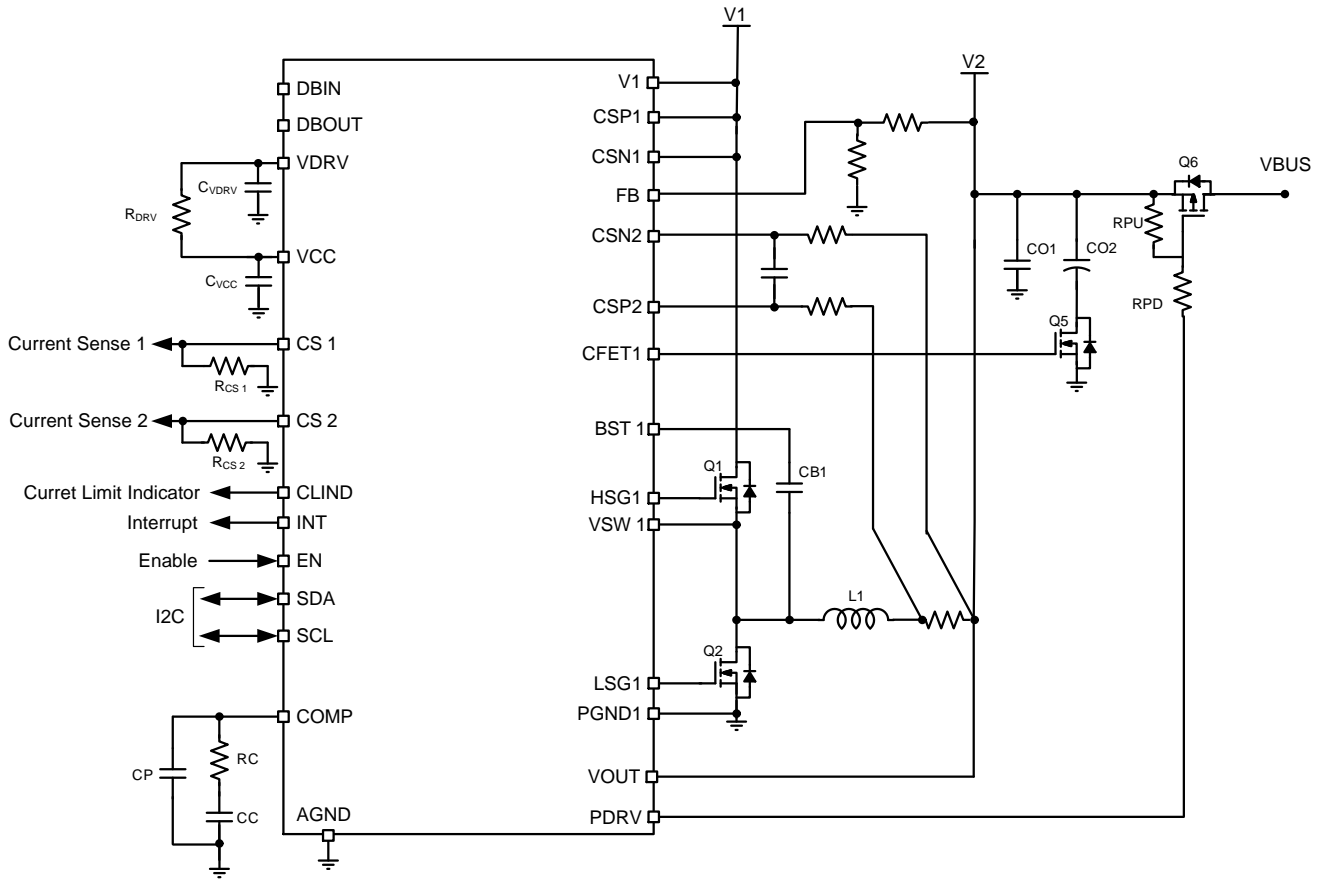


Figure 2. Typical Application Circuit (Rsense)

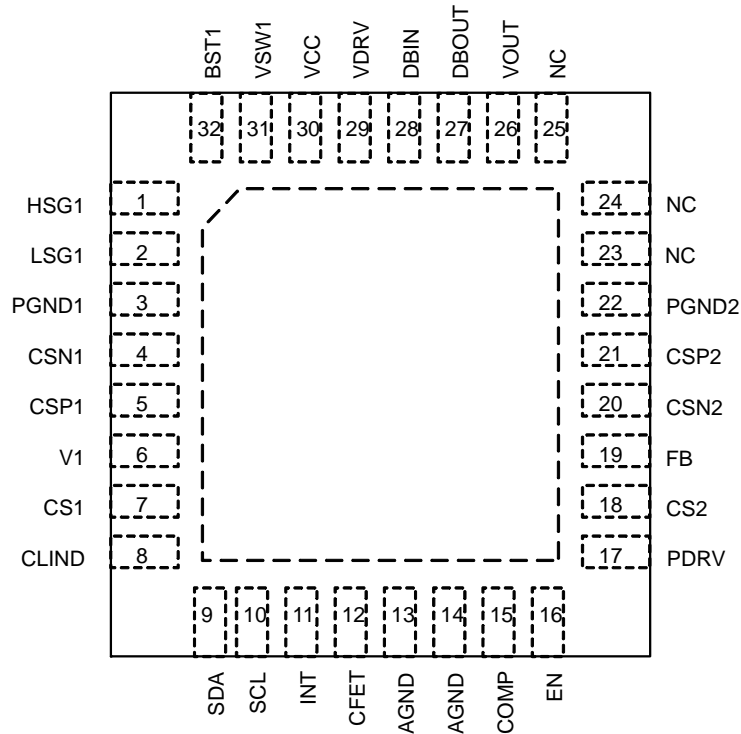


Figure 3. Pinout

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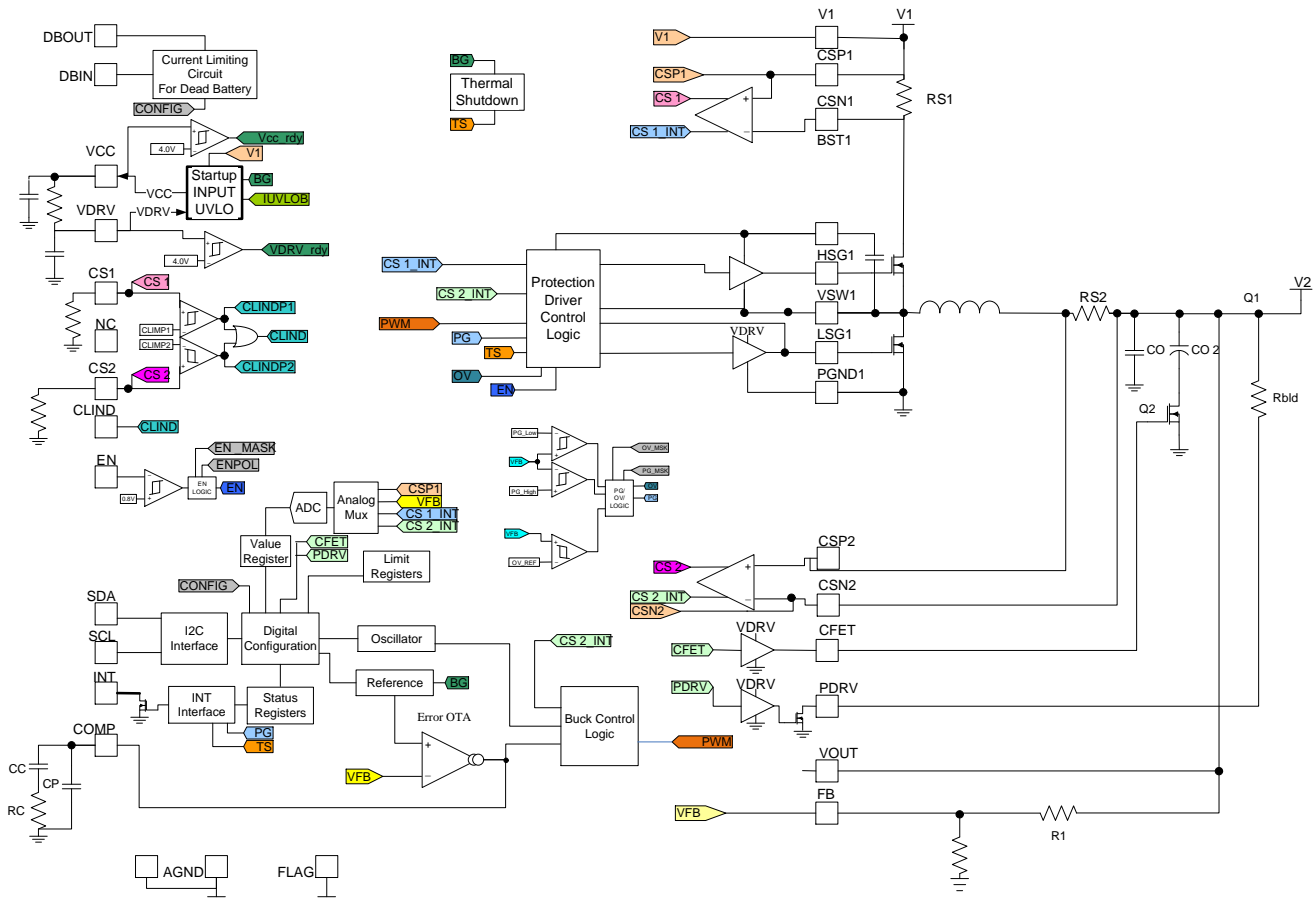


Figure 4. Block Diagram

Table 1. PIN FUNCTION DESCRIPTION

| Pin    | Pin Name | Description                                                                                                                                                                                                                                |
|--------|----------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1      | HSG1     | S1 gate drive. Drives the S1 N-channel MOSFET with a voltage equal to VDRV superimposed on the switch node voltage VSW1.                                                                                                                   |
| 2      | LSG1     | Drives the gate of the S2 N-channel MOSFET between ground and VDRV.                                                                                                                                                                        |
| 3, 22  | PGND     | Power ground for the low side MOSFET drivers. Connect these pins closely to the source of the bottom N-channel MOSFETs.                                                                                                                    |
| 4      | CSN1     | Negative terminal of the current sense amplifier.                                                                                                                                                                                          |
| 5      | CSP1     | Positive terminal of the current sense amplifier.                                                                                                                                                                                          |
| 6      | V1       | Input voltage of the converter                                                                                                                                                                                                             |
| 7      | CS1      | Current sense amplifier output. CS1 will source a current that is proportional to the voltage across CSP1/CSN1. Connect CS1 to a high impedance monitoring input.                                                                          |
| 8      | CLIND    | Open drain output to indicate that the CS1 or CS2 voltage has exceeded the I <sup>2</sup> C programmed limit.                                                                                                                              |
| 9      | SDA      | I <sup>2</sup> C interface data line.                                                                                                                                                                                                      |
| 10     | SCL      | I <sup>2</sup> C interface clock line.                                                                                                                                                                                                     |
| 11     | INT      | Interrupt is an open drain output that indicates the state of the output power, the internal thermal trip, and other I <sup>2</sup> C programmable functions.                                                                              |
| 12     | CFET     | Controlled drive of an external MOSFET that connects a bulk output capacitor to the output of the power converter. Necessary to adhere to low capacitance limits of the standard USB Specifications for power prior to USB PD negotiation. |
| 13, 14 | AGND     | The ground pin for the analog circuitry.                                                                                                                                                                                                   |
| 15     | COMP     | Output of the transconductance amplifier used for stability in closed loop operation.                                                                                                                                                      |

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**Table 1. PIN FUNCTION DESCRIPTION** (continued)

| Pin   | Pin Name | Description                                                                                                                                                                                                                                     |
|-------|----------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 16    | EN       | Precision enable starts the part and places it into default configuration when toggled.                                                                                                                                                         |
| 17    | PDRV     | The open drain output used to control a PMOSFET or connect to an external resistor.                                                                                                                                                             |
| 18    | CS2      | Current sense amplifier output. CS2 will source a current that is proportional to the voltage across CSP1/CSN1. Connect CS2 to a high impedance monitoring input.                                                                               |
| 19    | FB       | Feedback voltage of the output, negative terminal of the gm amplifier.                                                                                                                                                                          |
| 20    | CSN2     | Negative terminal of the current sense amplifier. Used for DCR sensing.                                                                                                                                                                         |
| 21    | CSP2     | Positive terminal of the current sense amplifier. Used for DCR sensing.                                                                                                                                                                         |
| 23–25 | NC       | No connection.                                                                                                                                                                                                                                  |
| 26    | VOUT     | Connect to the buck output voltage.                                                                                                                                                                                                             |
| 27    | DBOUT    | The output of the dead battery circuit which can also be used for the VCONN voltage supply.                                                                                                                                                     |
| 28    | DBIN     | The dead battery input to the converter where 5 V is applied. A 1 $\mu$ F capacitor should be placed close to the part to decouple this line.                                                                                                   |
| 29    | VDRV     | Internal voltage supply to the driver circuits. A 1 $\mu$ F capacitor should be placed close to the part to decouple this line.                                                                                                                 |
| 30    | VCC      | The VCC pin supplies power to the internal circuitry. The VCC is the output of a linear regulator which is powered from V1. Can be used to supply up to a 100 mA load. Pin should be decoupled with a 1 $\mu$ F capacitor for stable operation. |
| 31    | VSW1     | Switch Node. VSW1 pin swings from a diode voltage drop below ground up to V1.                                                                                                                                                                   |
| 32    | BST1     | Driver Supply. The BST1 pin swings from a diode voltage below VDRV up to a diode voltage below V1 + VDRV. Place a 0.1 $\mu$ F capacitor from this pin to VSW1.                                                                                  |
| 33    | THPAD    | Center pad, recommended to connect to AGND.                                                                                                                                                                                                     |

**Table 2. MAXIMUM RATINGS**

(Over operating free-air temperature range unless otherwise noted)

| Rating                               | Symbol   | Min                               | Max                                          | Unit |
|--------------------------------------|----------|-----------------------------------|----------------------------------------------|------|
| Input of the Dead Battery Circuit    | DBIN     | -0.3                              | 5.5                                          | V    |
| Output of the Dead Battery Circuit   | DBOUT    | -0.3                              | 5.5                                          | V    |
| Driver Input Voltage                 | VDRV     | -0.3                              | 5.5                                          | V    |
| Internal Regulator Output            | VCC      | -0.3                              | 5.5                                          | V    |
| Output of Current Sense Amplifiers   | CS1, CS2 | -0.3                              | 3.0                                          | V    |
| Current Limit Indicator              | CLIND    | -0.3                              | VCC + 0.3                                    | V    |
| Interrupt Indicator                  | INT      | -0.3                              | VCC + 0.3                                    | V    |
| Enable Input                         | EN       | -0.3                              | 5.5                                          | V    |
| I <sup>2</sup> C Communication Lines | SDA, SCL | -0.3                              | VCC + 0.3                                    | V    |
| Compensation Output                  | COMP     | -0.3                              | VCC + 0.3                                    | V    |
| V1 Power Stage Input Voltage         | V1       | -0.3                              | 32 V, 40 V (20 ns)                           | V    |
| Positive Current Sense               | CSP1     | -0.3                              | 32 V, 40 V (20 ns)                           | V    |
| Negative Current Sense               | CSN1     | -0.3                              | 32 V, 40 V (20 ns)                           | V    |
| Positive Current Sense               | CSP2     | -0.3                              | 32 V, 40 V (20 ns)                           | V    |
| Negative Current Sense               | CSN2     | -0.3                              | 32 V, 40 V (20 ns)                           | V    |
| Feedback Voltage                     | FB       | -0.3                              | 5.5                                          | V    |
| CFET Driver                          | CFET     | -0.3                              | VCC + 0.3                                    | V    |
| Driver Positive Rail                 | BST1     | -0.3 V wrt/PGND<br>-0.3 V wrt/VSW | 37 V, 40 V (20 ns) wrt/PGND<br>5.5 V wrt/VSW | V    |

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**Table 2. MAXIMUM RATINGS** (continued)

(Over operating free-air temperature range unless otherwise noted)

| Rating                                                                                                                                          | Symbol            | Min                               | Max                                         | Unit      |
|-------------------------------------------------------------------------------------------------------------------------------------------------|-------------------|-----------------------------------|---------------------------------------------|-----------|
| High Side Driver                                                                                                                                | HSG1              | -0.3 V wrt/PGND<br>-0.3 V wrt/VSW | 37 V, 40 V (20 ns) wrt/GND<br>5.5 V wrt/VSW | V         |
| Switching Node and Return Path of Driver                                                                                                        | VSW1              | -5.0 V                            | 32 V, 40 V (20 ns)                          | V         |
| Low Side Driver                                                                                                                                 | LSG1              | -0.3 V                            | 5.5                                         | V         |
| PMOSFET Driver                                                                                                                                  | PDRV              | -0.3                              | 40                                          | V         |
| Voltage Differential                                                                                                                            | AGND to PGND      | -0.3                              | 0.3                                         | V         |
| CSP1–CSN1, CSP2–CSN2 Differential Voltage                                                                                                       | CS1DIF,<br>CS2DIF | -0.5                              | 0.5                                         | V         |
| PDRV Maximum Current                                                                                                                            | PDRVI             | 0                                 | 10                                          | mA        |
| PDRV Maximum Pulse Current<br>(100 ms on time, with > 1 s interval)                                                                             | PDRVIPUL          | 0                                 | 200                                         | mA        |
| Maximum VCC Current                                                                                                                             | VCCI              | 0                                 | 80                                          | mA        |
| Operating Junction Temperature Range (Note 1)                                                                                                   | TJ                | -40                               | 150                                         | °C        |
| Operating Ambient Temperature Range                                                                                                             | TA                | -40                               | 100                                         | °C        |
| Storage Temperature Range                                                                                                                       | TSTG              | -55                               | 150                                         | °C        |
| Thermal Characteristics (Note 2)<br>QFN 32 5mm x 5mm<br>Maximum Power Dissipation @ TA = 25°C<br>Thermal Resistance Junction-to-Air with Solder | PD<br>RθJA        |                                   | 4.1<br>30                                   | W<br>°C/W |
| Lead Temperature Soldering (10 sec):<br>Reflow (SMD styles only) Pb-Free (Note 3)                                                               | RF                |                                   | 260 Peak                                    | °C        |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The maximum package power dissipation limit must not be exceeded.
2. The value of  $\theta_{JA}$  is measured with the device mounted on a 3in x 3in, 4 layer, 0.062 inch FR-4 board with 1.5 oz. copper on the top and bottom layers and 0.5 ounce copper on the inner layers, in a still air environment with  $T_A = 25^\circ\text{C}$ .
3. 60–180 seconds minimum above  $237^\circ\text{C}$ .

**Table 3. ELECTRICAL CHARACTERISTICS**

(V1 = 12 V, V<sub>out</sub> = 5.0 V, T<sub>A</sub> = +25°C for typical value; -40°C < T<sub>A</sub> < 100°C for min/max values unless noted otherwise)

| Parameter                     | Symbol                | Test Conditions                                                   | Min  | Typ  | Max | Units |
|-------------------------------|-----------------------|-------------------------------------------------------------------|------|------|-----|-------|
| <b>Power Supply</b>           |                       |                                                                   |      |      |     |       |
| V1 Operating Input Voltage    | V1                    |                                                                   | 4.5  |      | 28  | V     |
| VDRV Operating Input Voltage  | VDRV                  |                                                                   | 4.5  | 5    | 5.5 | V     |
| VCC UVLO Rising Threshold     | VCC <sub>START</sub>  |                                                                   |      | 4.26 |     | V     |
| UVLO Hysteresis for VCC       | VCCV <sub>HYS</sub>   | Falling Hysteresis                                                |      | 320  |     | mV    |
| VDRV UVLO Rising Threshold    | VDRV <sub>START</sub> |                                                                   |      | 4.27 |     | V     |
| UVLO Hysteresis for VDRV      | VDRV <sub>HYS</sub>   | Falling Hysteresis                                                |      | 340  |     | mV    |
| VCC Output Voltage            | VCC                   | With no external load                                             | 4.96 | 5    |     | V     |
| VCC Drop Out Voltage          | VCCDROOP              | 30 mA load                                                        |      | 160  |     | mV    |
| VCC Output Current Limit      | IOU <sub>VCC</sub>    | VCC Loaded to 4.3 V                                               | 80   | 97   |     | mA    |
| V1 Shutdown Supply Current    | IVCC_SD               | EN = 0 V, 4.2 V ≤ V1 ≤ 28 V                                       |      | 6.7  | 7.7 | mA    |
| VDRIVE Switching Current Buck | IV1_SW                | EN = 5 V, C <sub>gate</sub> = 2.2 nF,<br>VSW = 0 V, FSW = 600 kHz |      | 15   |     | mA    |

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**Table 3. ELECTRICAL CHARACTERISTICS** (continued)

(V<sub>1</sub> = 12 V, V<sub>out</sub> = 5.0 V, T<sub>A</sub> = +25°C for typical value; -40°C < T<sub>A</sub> < 100°C for min/max values unless noted otherwise)

| Parameter                         | Symbol  | Test Conditions                                              | Min        | Typ | Max      | Units   |
|-----------------------------------|---------|--------------------------------------------------------------|------------|-----|----------|---------|
| <b>Voltage Output</b>             |         |                                                              |            |     |          |         |
| Voltage Output Accuracy           | VFB     | DAC_TARGET = 00110010                                        | 0.495      | 0.5 | 0.505    | V       |
|                                   |         | DAC_TARGET = 01111000                                        | 1.188      | 1.2 | 1.212    |         |
|                                   |         | DAC_TARGET = 11001000                                        | 1.98       | 2.0 | 2.02     |         |
| Voltage Accuracy Over Temperature | VOUTERT | -40°C < T <sub>A</sub> < 100°C<br>VFB > 0.5 V<br>VFB < 0.5 V | -1.0<br>-5 |     | 1.0<br>5 | %<br>mV |
|                                   | VOUTER  | T <sub>A</sub> = 25°C<br>VFB > 0.5 V                         | -0.45      |     | 0.45     | %       |

### Transconductance Amplifier

|                                 |       |               |    |     |  |     |
|---------------------------------|-------|---------------|----|-----|--|-----|
| Gain Bandwidth Product          | GBW   | 3 db (Note 4) |    | 5.2 |  | MHz |
| Transconductance                | GM1   | Default       |    | 500 |  | μS  |
| Max Output Source Current limit | GMSOC |               | 60 | 83  |  | μA  |
| Max Output Sink Current limit   | GMSIC |               | 60 | 84  |  | μA  |
| Voltage Ramp                    | Vramp |               |    | 1.4 |  | V   |

### Internal BST Diode

|                              |           |                                                                |      |      |      |    |
|------------------------------|-----------|----------------------------------------------------------------|------|------|------|----|
| Forward Voltage Drop         | VFBOT     | I <sub>F</sub> = 10 mA, T <sub>A</sub> = 25°C                  | 0.35 | 0.46 | 0.55 | V  |
| Reverse-Bias Leakage Current | DIL       | BST-VSW = 5 V<br>V <sub>SW</sub> = 28 V, T <sub>A</sub> = 25°C |      | 0.05 | 1    | μA |
| BST-VSW UVLO                 | BST1_UVLO | Rising (Note 4)                                                |      | 3.5  |      | V  |
| BST-VSW Hysteresis           | BST_HYS   | (Note 4)                                                       |      | 300  |      | mV |

### Oscillator

|                               |       |                                                                  |      |      |      |     |
|-------------------------------|-------|------------------------------------------------------------------|------|------|------|-----|
| Oscillator Frequency          | FSW_0 | FSW = 000, default                                               | 528  | 600  | 672  | kHz |
|                               | FSW_1 | FSW = 001                                                        | 132  | 150  | 168  | kHz |
|                               | FSW_7 | FSW = 110                                                        | 1056 | 1200 | 1344 | kHz |
| Oscillator Frequency Accuracy | FSWE  |                                                                  | -12  |      | 12   | %   |
| Minimum On Time               | MOT   | Measured at 10% to 90% of VCC,<br>-40°C < T <sub>A</sub> < 100°C |      | 50   |      | ns  |
| Minimum Off Time              | MOFT  | Measured at 90% to 10% of VCC,<br>-40°C < T <sub>A</sub> < 100°C |      | 90   |      | ns  |

### INT Thresholds

|                                |          |                                    |  |            |     |    |
|--------------------------------|----------|------------------------------------|--|------------|-----|----|
| Interrupt Low Voltage          | VINTI    | IINT(sink) = 2 mA                  |  |            | 0.2 | V  |
| Interrupt High Leakage Current | INII     | 3.3 V                              |  | 3          | 100 | nA |
| Interrupt Startup Delay        | INTPG    | Soft Start end to PG positive edge |  | 2.1        |     | ms |
| Interrupt Propagation Delay    | PGI      | Delay for power good in            |  | 3.3        |     | ms |
|                                | PGO      | Delay for power good out           |  | 100        |     | ns |
| Power Good Threshold           | PGTH     | Power Good in from high            |  | 105        |     | %  |
|                                | PGTH     | Power Good in from low             |  | 95         |     | %  |
|                                | PGTHYS   | PG falling hysteresis              |  | 2.5        |     | %  |
| FB Overvoltage Threshold       | FB_OV    |                                    |  | 140        |     | %  |
| Overvoltage Propagation Delay  | VFB_OVDL |                                    |  | 1<br>Cycle |     |    |

4. Ensured by design. Not production tested.

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**Table 3. ELECTRICAL CHARACTERISTICS** (continued)

(V<sub>1</sub> = 12 V, V<sub>out</sub> = 5.0 V, T<sub>A</sub> = +25°C for typical value; -40°C < T<sub>A</sub> < 100°C for min/max values unless noted otherwise)

| Parameter                               | Symbol | Test Conditions                                                       | Min | Typ | Max | Units |
|-----------------------------------------|--------|-----------------------------------------------------------------------|-----|-----|-----|-------|
| <b>External Current Sense (CS1,CS2)</b> |        |                                                                       |     |     |     |       |
| Positive Current Measurement High       | CS10   | CSP1-CSN1 or CSP2-CSN2 = 100 mV                                       |     | 500 |     | μA    |
| Transconductance Gain Factor            | CSGT   | Current Sense Transconductance<br>V <sub>sense</sub> = 1 mV to 100 mV |     | 5   |     | mS    |
| Transconductance Deviation              | CSGE   |                                                                       | -20 |     | 20  | %     |
| Current Sense Common Mode Range         | CSCMMR |                                                                       | 3   |     | 28  | V     |
| -3dB Small Signal Bandwidth             | CSBW   | VSENSE (AC) = 10 mVPP,<br>RGAIN = 10 kΩ (Note 4)                      |     | 30  |     | MHz   |
| Input Sense Voltage Full Scale          | ISVFS  |                                                                       |     |     | 100 | mV    |
| CS Output Voltage Range                 | CSOR   | VSENSE = 100 mV Rset = 6k                                             | 0   |     | 3   | V     |

### External Current Limit (CLIND)

|                                     |        |                        |     |     |     |    |
|-------------------------------------|--------|------------------------|-----|-----|-----|----|
| Current Limit Indicator Output Low  | CLINDL | Input current = 500 μA |     | 10  | 100 | mV |
| Current Limit Indicator Output High | CLINDH | Input current = 500 μA | 4.0 | 5.0 |     | V  |

### Internal Current Sense

|                                     |       |                    |     |     |      |     |
|-------------------------------------|-------|--------------------|-----|-----|------|-----|
| Internal Current Sense Gain for PWM | ICG   | CSPx-CSNx = 100 mV | 9.2 | 9.9 | 10.5 | V/V |
| Positive Peak Current Limit Trip    | PPCLT | INT_CL = 00        | 34  | 39  | 44   | mV  |
| Negative Valley Current Limit Trip  | NVCLT | INT_CL_NEG = 00    | 31  | 40  | 45   | mV  |

### Switching MOSFET Drivers

|                                 |        |                   |  |     |  |    |
|---------------------------------|--------|-------------------|--|-----|--|----|
| HSG Pullup Resistance           | HSG_PU | BST-VSW = 4.5 V   |  | 2.9 |  | Ω  |
| HSG Pulldown Resistance         | HSG_PD | BST-VSW = 4.5 V   |  | 1.1 |  | Ω  |
| LSG Pullup Resistance           | LSG_PU | LSG -PGND = 2.5 V |  | 3.4 |  | Ω  |
| LSG Pulldown Resistance         | LSG_PD | LSG -PGND = 2.5 V |  | 1.1 |  | Ω  |
| HSG Falling to LSG Rising Delay | HSLSD  |                   |  | 15  |  | ns |
| LSG Falling to HSG Rising Delay | LSHSD  |                   |  | 15  |  | ns |

### CFET

|                           |        |                                                                   |  |     |  |    |
|---------------------------|--------|-------------------------------------------------------------------|--|-----|--|----|
| CFET Drive Voltage        | CFETDV |                                                                   |  | VCC |  | V  |
| Source/Sink Current       | CFETSS | CFET clamped to 2 V                                               |  | 2   |  | μA |
| Pull Down Delay           | CFETD  | Measured at 10% to 90% of VCC,<br>-40°C < T <sub>A</sub> < 100°C  |  | 10  |  | ms |
| CFET Pull Down Resistance | CFETR  | Measured with 1 mA Pull up Current, after 10 ms rising edge delay |  | 1.3 |  | kΩ |

### Slew Rate/Soft Start

|                     |       |                                                      |  |              |  |       |
|---------------------|-------|------------------------------------------------------|--|--------------|--|-------|
| Charge Slew Rate    | SLEWP | Slew = 00, FB = 0.1 VOUT<br>Slew = 11, FB = 0.1 VOUT |  | 0.6<br>4.8   |  | mV/μs |
| Discharge Slew Rate | SLEWN | Slew = 00, FB = 0.1 VOUT<br>Slew = 11, FB = 0.1 VOUT |  | -0.6<br>-4.8 |  | mV/μs |

### Dead Battery/VCONN

|                                  |        |                                                                    |     |     |      |    |
|----------------------------------|--------|--------------------------------------------------------------------|-----|-----|------|----|
| Dead Battery Input Voltage Range | VDB    |                                                                    | 4.5 | 5   | 5.25 | V  |
| Dead Battery Output Voltage      | VIO    | VDB = 5 V, -40°C < T <sub>A</sub> < 100°C,<br>Output Current 32 mA | 4   | 4.7 | 5    | V  |
| Dead Battery Current Limit       | DB_LIM | VDB = 5 V, V1 greater than 2 V                                     | 29  | 57  |      | mA |

4. Ensured by design. Not production tested.



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**Table 3. ELECTRICAL CHARACTERISTICS** (continued)

(V<sub>1</sub> = 12 V, V<sub>out</sub> = 5.0 V, T<sub>A</sub> = +25°C for typical value; -40°C < T<sub>A</sub> < 100°C for min/max values unless noted otherwise)

| Parameter                       | Symbol   | Test Conditions            | Min  | Typ  | Max  | Units |
|---------------------------------|----------|----------------------------|------|------|------|-------|
| <b>Enable</b>                   |          |                            |      |      |      |       |
| EN High Threshold Voltage       | ENHT     | EM_MASK = ENPU = ENPOL = 0 |      | 800  | 820  | mV    |
| EN Low Threshold Voltage        | ENLT     |                            | 640  | 667  |      | mV    |
| EN Pull Up Current              | IEN_UP   | EN = 0 V                   |      | 5    |      | μA    |
| EN Pull Down Current            | IEN_DN   | EN = VCC                   |      | 5    |      | μA    |
| <b>I<sup>2</sup>C Interface</b> |          |                            |      |      |      |       |
| Voltage Threshold               | I2CVTH   |                            | 0.95 | 1    | 1.05 | V     |
| Propagation Delay               | I2CPD    | (Note 4)                   |      | 25   |      | ns    |
| Communication Speed             | I2CSP    | (Note 4)                   |      |      | 1    | MHz   |
| <b>Internal ADC</b>             |          |                            |      |      |      |       |
| Range                           | ADCRN    |                            | 0    |      | 2.55 | V     |
| LSB Value                       | ADCLSB   | (Note 4)                   |      | 20   |      | mV    |
| Error                           | ADCFE    | (Note 4)                   |      |      | 1    | LSB   |
| <b>Thermal Shutdown</b>         |          |                            |      |      |      |       |
| Thermal Shutdown Threshold      | TSD      | (Note 4)                   |      | 151  |      | °C    |
| Thermal Shutdown Hysteresis     | TSDHYS   | (Note 4)                   |      | 28   |      | °C    |
| <b>PDRV</b>                     |          |                            |      |      |      |       |
| PDRV Operating Range            |          |                            | 0    |      | 28   | V     |
| PDRV Leakage Current            | PDRV_IDS | FET OFF, VPDRV = 28 V      |      | 480  |      | nA    |
| PDRV Saturation Voltage         | PDRV_VDS | ISNK = 10 mA               |      | 0.20 |      | V     |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Ensured by design. Not production tested.

APPLICATION INFORMATION

**Feedback and Output Voltage Profile**

The feedback of the converter output voltage is connected to the FB pin of the device through a resistor divider. Internally FB is connected to the inverting input of the internal transconductance error amplifier. The non-inverting input of the gm amplifier is connected to the internal reference. The internal reference voltage is by default 0.5 V. Therefore, for example, a 10:1 resistor divider from the converter output to the FB will set the output

voltage to 5 V in default. The reference voltage can be adjusted with 10 mV(default) or 5 mV steps from 0.3 V to 2.55 V through the voltage profile register (01H), which makes the continuous output voltage profile possible through an external resistor divider. For example, if the external resistor divider has a 10:1 ratio, the output voltage profile will be able to vary from 3 V to 25.5 V with 100 mV steps but not above V1 voltage.

**Table 4. VOLTAGE PROFILE SETTINGS**

| dac_taget |       |       |       |       |       |       |       | dac_target_LSB | Voltage Profile Hex Value | Reference Voltage (mV) |
|-----------|-------|-------|-------|-------|-------|-------|-------|----------------|---------------------------|------------------------|
| bit_8     | bit_7 | bit_6 | bit_5 | bit_4 | bit_3 | bit_2 | bit_1 |                |                           |                        |
| 0         | 0     | 0     | 0     | 0     | 0     | 0     | 0     | 0              | 00H                       | Reserved               |
| 0         | 0     | 0     | 0     | 1     | 0     | 0     | 0     | 1              | 00H                       | Reserved               |
| 0         | 0     | 0     | 0     | 0     | 0     | 0     | 1     | 0              | 01H                       | Reserved               |
| ...       | ...   | ...   | ...   | ...   | ...   | ...   | ...   | ...            | ...                       | ...                    |
| 0         | 0     | 0     | 1     | 1     | 1     | 0     | 1     | 1              | 1DH                       | Reserved               |
| 0         | 0     | 0     | 1     | 1     | 1     | 1     | 0     | 0              | 1EH                       | 300                    |
| 0         | 0     | 0     | 1     | 1     | 1     | 1     | 0     | 1              | 1EH                       | 305                    |
| ...       | ...   | ...   | ...   | ...   | ...   | ...   | ...   | ...            | ...                       | ...                    |
| 0         | 0     | 1     | 1     | 0     | 0     | 1     | 0     | 0              | 32H                       | 500 (Default)          |
| ...       | ...   | ...   | ...   | ...   | ...   | ...   | ...   | ...            | ...                       | ...                    |
| 1         | 1     | 0     | 0     | 1     | 0     | 0     | 0     | 0              | C8H                       | 2000                   |
| ...       | ...   | ...   | ...   | ...   | ...   | ...   | ...   | ...            | ...                       | ...                    |
| 1         | 1     | 1     | 1     | 1     | 1     | 1     | 1     | 0              | FFH                       | 2550                   |
| 1         | 1     | 1     | 1     | 1     | 1     | 1     | 1     | 1              | FFH                       | 2555                   |

**Transconductance Voltage Error Amplifier**

To maintain loop stability under a large change in capacitance, the NCP81231 can change the gm of the internal transconductance error amplifier from 87  $\mu$ S to

1000  $\mu$ S allowing the DC gain of the system to be increased more than a decade triggered by the adding and removal of the bulk capacitance or in response to another user input. The default transconductance is 500  $\mu$ S.

**Table 5. AVAILABLE TRANSCONDUCTANCE SETTING**

| AMP_2 | AMP_1 | AMP_0 | Amplifier GM Value ( $\mu$ S) |
|-------|-------|-------|-------------------------------|
| 0     | 0     | 0     | 87                            |
| 0     | 0     | 1     | 100                           |
| 0     | 1     | 0     | 117                           |
| 0     | 1     | 1     | 333                           |
| 1     | 0     | 0     | 400                           |
| 1     | 0     | 1     | 500                           |
| 1     | 1     | 0     | 667                           |
| 1     | 1     | 1     | 1000                          |

**Programmable Slew Rate**

The slew rate of the NCP81231 is controlled via the I<sup>2</sup>C registers with the default slew rate set to 0.6 mV/μs (FB = 0.1 VOUT, assume the resistor divider ratio is 10:1) which is the slowest allowable rate change. The slew rate is used when the output voltage starts from 0 V to a user selected profile level, changing from one profile to another, or when the output voltage is dynamically changed. The output voltage is divided by a factor of the external resistor divider and connected to FB pin. The 9 Bit DAC is used to increase the reference voltage in 10 or 5 mV increments. The

slew rate is decreased by using a slower clock that results in a longer time between voltage steps, and conversely increases by using a faster clock. The step monotonicity depends on the bandwidth of the converter where a low bandwidth will result in a slower slew rate than the selected value. The available slew rates are shown in Table 6. The selected slew rate is maintained unless the current limit is tripped, in which case the increased voltage will be governed by the positive current limit until the output voltage falls or the fault is cleared.

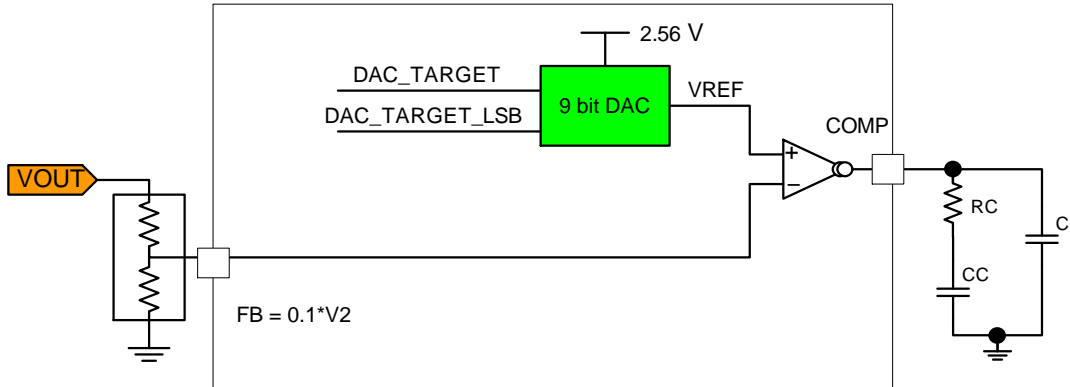


Figure 5. Slew Rate Limiting Block Diagram and Waveforms

Table 6. SLEW RATE SELECTION

| Slew Bits | Soft Start or Voltage Transition (FB = 0.1*VOUT) |
|-----------|--------------------------------------------------|
| Slew_0    | 0.61 mV/μs                                       |
| Slew_1    | 1.2 mV/μs                                        |
| Slew_2    | 2.4 mV/μs                                        |
| Slew_3    | 4.9 mV/μs                                        |

The discharge slew rate is accomplished in much the same way as the charging except the reference voltage is decreased rather than increased.

**Soft Start**

During a 0 V soft start, standard converters can start in synchronous mode and have a monotonic rising of output

voltage. If a prebias exists on the output and the converter starts in synchronous mode, the prebias voltage will be discharged. The NCP81231 controller ensures that if a prebias is detected, the soft start is completed in a non-synchronous mode to prevent the output from discharging.

**Frequency Programming**

The switching frequency of the NCP81231 can be programmed from 150 kHz to 1.2 MHz via the I<sup>2</sup>C interface. The default switching frequency is set to 600 kHz. Once the part is enabled, the frequency is set and cannot be changed while the part remains enabled. The part must be disabled with no switching prior to writing the frequency bits into the appropriate I<sup>2</sup>C register.

Table 7. FREQUENCY PROGRAMMING TABLE

| Name  | Bit       | Definition        | Description                                                                                                                                                                                         |
|-------|-----------|-------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Freq1 | 03H [2:0] | Frequency Setting | 3 Bits that Control the Switching Frequency from 150 kHz to 1 MHz.<br>000: 600 kHz<br>001: 150 kHz<br>010: 300 kHz<br>011: 450 kHz<br>100: 750 kHz<br>101: 900 kHz<br>110: 1.2 MHz<br>111: Reserved |

**100% Duty Cycle Operation**

NCP81231 can operate in a 100% duty cycle mode when the high side switch works as a bypass switch. A detection circuit will constantly monitor the high side gate voltage and turn on low side switch to refresh the boost capacitor when the voltage across the boost capacitor is below the boost UVLO voltage. If the system stays in the 100% duty cycle operation, the output will always follow the input regardless the COMP voltage and COMP is likely to creep up. If a fast COMP recovery is required, the following clamping circuitry can be considered with a larger than 1.5 V clamping voltage set as the target.

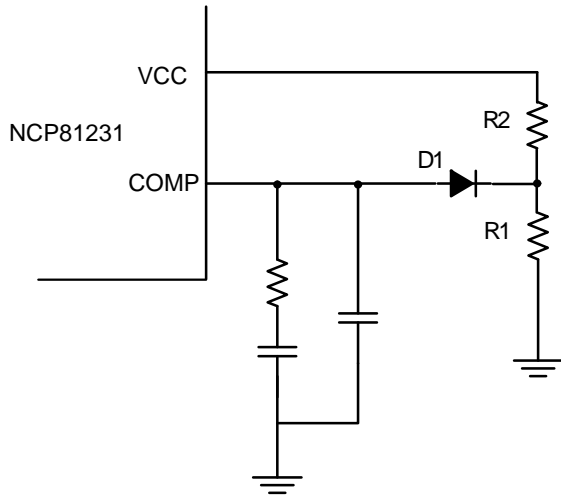


Figure 6. External Comp Clamping Circuit

**Current Sense Amplifiers**

Internal differential amplifiers measure the potential between the terminal CSP1/CSN1 or CSP2/CSN2. The potential difference between CSPx and CSNx is level shifted from the high voltage domain to the low voltage VCC domain.

Both current sense signals can be monitored externally by CS1 and CS2 pins. They are fixed gm amplifier outputs, allowing users to set output gain by shunting resistors. CS1 correlates to the CSP1/CSN1 reading, CS2 correlates to the CSP2/CSN2 reading. When not used, CSP1/CSN pin can be shorted therefore CS1 reading is omitted.

NCP81231 also uses CSP2/CSN2 current sense signal for current mode modulation and cycle by cycle positive and negative peak current limiting. The inputs of CSP2/CSN2 can be a current sense resistor or configured for inductor DCR sensing shown as Figure 7. A resistor Rs1 connects from switch node to CSP2 and Rs2 connects from the output voltage to CSN2 respectively. Two capacitors, Cs1 and Cs2, are common mode filtering capacitors from CSP2 and CSN2 to the ground. Choose  $R_{s1}=R_{s2}=R_s$ ,  $C_{s1}=C_{s2}=C_s$ ; In order to replicate inductor current sensing information,  $R_s \cdot C_s$  needs to be equal or slightly higher than the ratio of output inductance over its DC resistance or  $L/DCR$ . Additional resistor network may be added to expand the actual current limit tripping range.

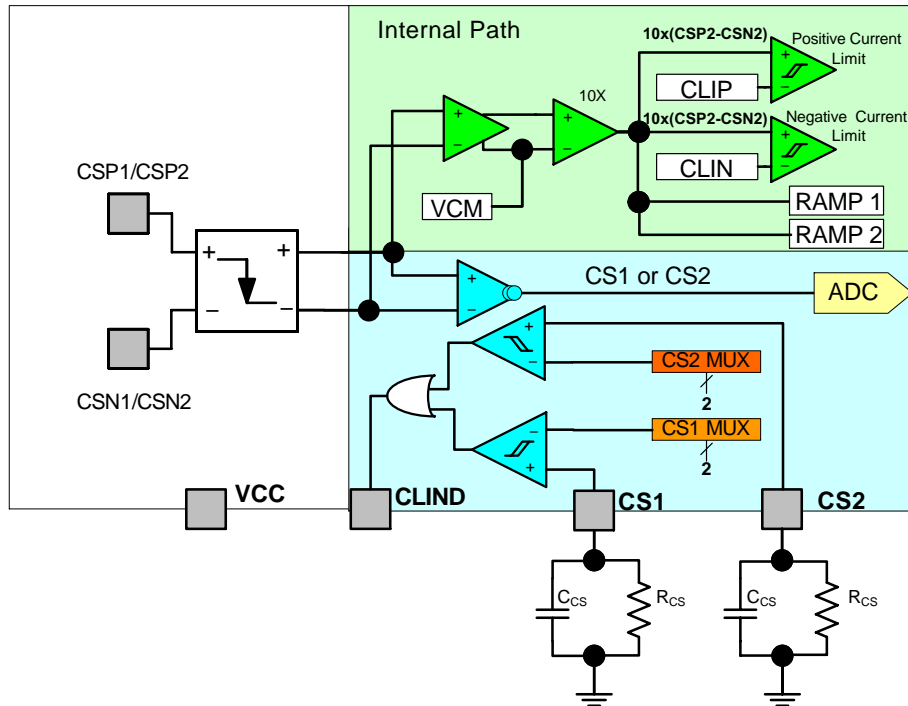


Figure 7. Block Diagram for Current Sense Channel

# NCP81231

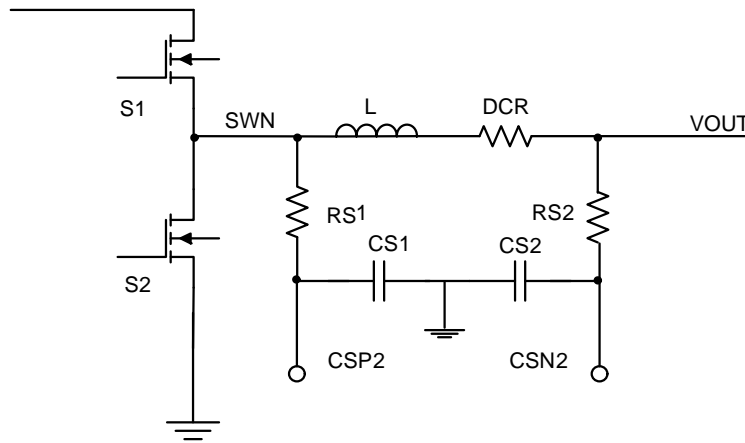


Figure 8. Inductor DCR Sensing Using CSP2/CSN2

### Positive Current Limit Internal Path

The NCP81231 has a pulse by pulse current limiting function activated when a positive current limit triggers. When a positive current limit is triggered, the current pulse is truncated. For NCP81231, the CSP2/CSN2 pins will be the positive current limit sense channel.

The S1 switch is turned off to limit the energy during an over current event. The current limit is reset every switching cycle and waits for the next positive current limit trigger. In

this way, current is limited on a pulse by pulse basis. Pulse by pulse current limiting is advantageous for limiting energy into a load in over current situations but are not up to the task of limiting energy into a low impedance short. To address the low impedance short, the NCP81231 will go to latch up mode if pulse by pulse current limiting continues for more than 4 cycles. Toggling the enable pin or resetting the input voltage (V1) will clear the latched OCP fault.

Table 8. INTERNAL PEAK CURRENT LIMIT

| CLIP_1 | CLIP_0 | CLIM delta Value (mV) | CSP2–CSN2 (mV) | Trip Current Inductor DCR = 2 mΩ (A) |
|--------|--------|-----------------------|----------------|--------------------------------------|
| 0      | 0      | 380                   | 38             | 19                                   |
| 0      | 1      | 230                   | 23             | 11.5                                 |
| 1      | 0      | 110                   | 11             | 5.5                                  |
| 1      | 1      | 700                   | 70             | 35                                   |

### External Path (CS1, CS2, CLIND)

The voltage drop across CSP1/CSN1 or CSP2/CSN2 as a result of the load can be observed on the CS1 and CS2 pins. The voltage drop is converted into a current by a transconductance amplifier with a typical GM of 5 mS. The final gain of the output is determined by the end users selection of the R<sub>CS</sub> resistors or the inductor DCR resistor. The output voltage of the CS pin can be calculated from Equation 1. The user must be careful to keep the dynamic range below 3.0 V when considering the maximum short circuit current.

$$\begin{aligned}
 V_{CS} &= (I_{LOAD\_MAX} * R_{SENSE} * Trans) * R_{CS} \rightarrow \\
 \rightarrow 2.967 \text{ V} &= (8.5 \text{ A} * 5 \text{ m}\Omega * 5 \text{ mS}) * 13.96 \text{ k}\Omega \\
 R_{CS} &= \frac{V_{CS}}{I_{LOAD} * R_{SENSE} * Trans} \rightarrow \\
 \rightarrow 13.96 \text{ k}\Omega &= \frac{2.967 \text{ V}}{8.5 \text{ A} * 5 \text{ m}\Omega * 5 \text{ mS}} \quad (\text{eq. 1})
 \end{aligned}$$

The speed and accuracy of the dual amplifier stage allows the reconstruction of the input and output current signal, creating the ability to limit the peak current. If the user would like to limit the mean DC current of the switch, a capacitor can be placed in parallel with the R<sub>CS</sub> resistors.

The external CS voltages are connected to 2 high speed low offset comparators. The comparators output can be used to suspend operation until reset or restart of the part depending on I<sup>2</sup>C configuration. When one of the comparators trips if not masked, the external CLIND flag is triggered to indicate that the internal comparator has exceeded the preset limit. The default comparator setting is 250 mV which is a limit of 500 mA with a current sense resistor of 5 mΩ and an R<sub>CS</sub> resistor of 20 kΩ. The block diagram in Figure 9 shows the programmable comparators and the settings are shown in Table 9.

# NCP81231

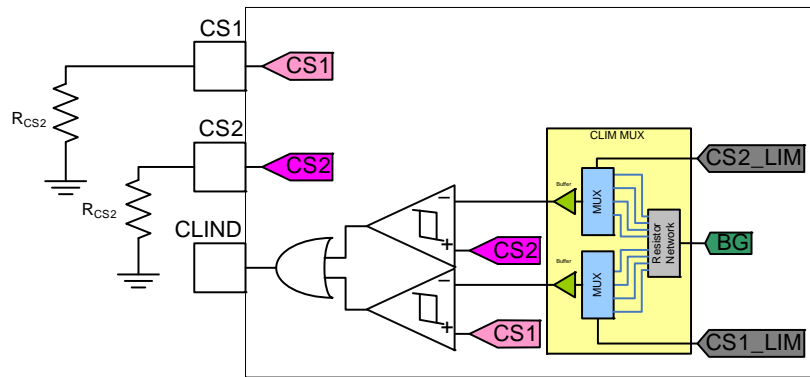


Figure 9. Block Diagram for CLIM Comparator

Table 9. REGISTER SETTING FOR THE CLIM COMPARATORS

| CLIMx_1 | CLIMx_0 | CSx_LIM (V) | Current at RSENSE = 5 mΩ<br>RSET = 20 kΩ (A) | Current at RSENSE = 5 mΩ<br>RSET = 10 kΩ (A) |
|---------|---------|-------------|----------------------------------------------|----------------------------------------------|
| 0       | 0       | 0.25        | .5                                           | 1                                            |
| 0       | 1       | 0.75        | 1.5                                          | 3                                            |
| 1       | 0       | 1.5         | 3                                            | 6                                            |
| 1       | 1       | 2.5         | 5                                            | 10                                           |

## Overvoltage Protection (OVP)

When the divided output voltage is 140% (typical) above the internal reference voltage, a latched OV fault will be triggered. At 0 V reference voltage, it's easy to trigger OVP falsely. So one should avoid using output voltage profile under 0.3 V for safety in normal operation. When 0 V output voltage is needed, one can disable NCP81231 by pulling EN pin down, instead of setting output voltage profile to 0 via I2C. Toggling the enable pin will not clear the latched OVP fault. Only resetting the input voltage (V1) can clear it.

## Power Good Monitor (PG)

NCP81231 provides two window comparators to monitor the internal feedback voltage. The target voltage window is  $\pm 5\%$  of the reference voltage (typical). Once the feedback voltage is within the power good window, a power good indication is asserted once a 3.3 ms timer has expired. If the feedback voltage falls outside a  $\pm 7\%$  window for greater than 1 switching cycle, the power good register is reset. Power good is indicated on the INT pin if the related I2C register is set to display the PG state. During startup, INT is set until the feedback voltage is within the specified range for 3.3 ms.

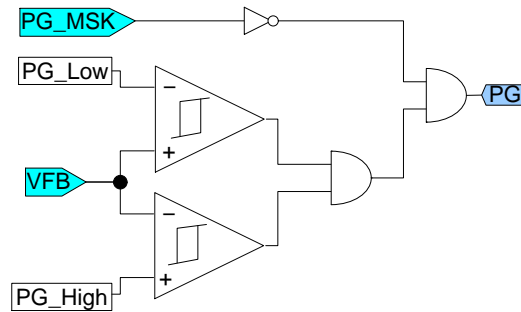


Figure 10. PG Block Diagram

Table 10. POWER GOOD MASKING

| PG_MSK | Description                       |
|--------|-----------------------------------|
| 0      | PG Action and Indication Unmasked |
| 1      | PG Action and Indication Masked   |

## Thermal Shutdown

The NCP81231 protects itself from overheating with an internal thermal shutdown circuit. If the junction temperature exceeds the thermal shutdown threshold (typically 150°C), all MOSFETs will be driven to the off state, and the part will wait until the temperature decreases to an acceptable level. The fault will be reported to the fault register and the INT flag will be set unless it is masked. When the junction temperature drops below 125°C (typical), the part will discharge the output voltage to 0 V.

**CFET Turn On**

The CFET is used to engage the output bulk capacitance after successful negotiations between a consumer and a provider. The USB Power Delivery Specification requires that no more than 30  $\mu\text{F}$  of capacitance be present on the VBUS rail when sinking power. Once the consumer and provider have completed a power role swap, a larger capacitance can be added to the output rail to accommodate a higher power level. The bulk capacitance must be added in such a way as to minimize current draw and reduce the voltage perturbation of the bus voltage. The NCP81231

incorporates a right drive circuit that regulates current into the gate of the MOSFET such that the MOSFET turns on slowly reducing the drain to source resistance gradually. Once the transition from high to low has occurred in a controlled way, a strong pulldown driver is used to ensure normal operation does not turn on the power N-MOSFET engaging the bulk capacitance. The CFET must be activated through the I<sup>2</sup>C interface where it can be engaged and disengaged. The default state is to have the CFET disengaged.

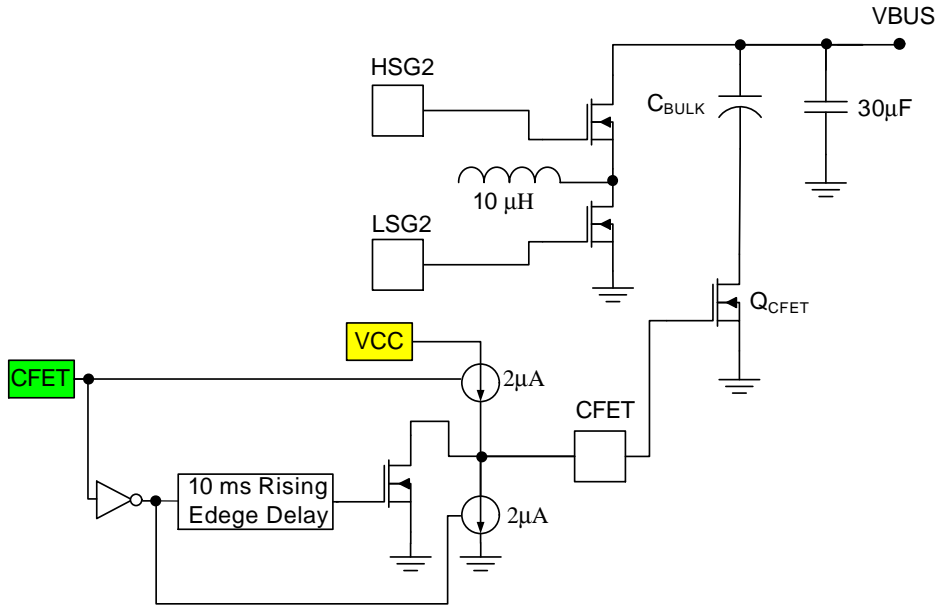


Figure 11. CFET Drive

Table 11. CFET ACTIVATION TABLE

| CFET_0 | Description         |
|--------|---------------------|
| 0      | CFET Drive Pulldown |
| 1      | CFET Drive Pull Up  |

**PFET Drive**

The PMOS drive is an open drain output used to control the turn on and turn off of PMOSFET switches at a floating potential or to create an external discharging path. The RDSon of the pulldown NMOSFET is typically 20  $\Omega$  allowing the user to quickly turn on for a fast output discharge or to control the external pass FETs.

Table 12. PFET ACTIVATION TABLE

| PFET_DRV | Description        |
|----------|--------------------|
| 0        | NFET OFF (Default) |
| 1        | NFET ON            |

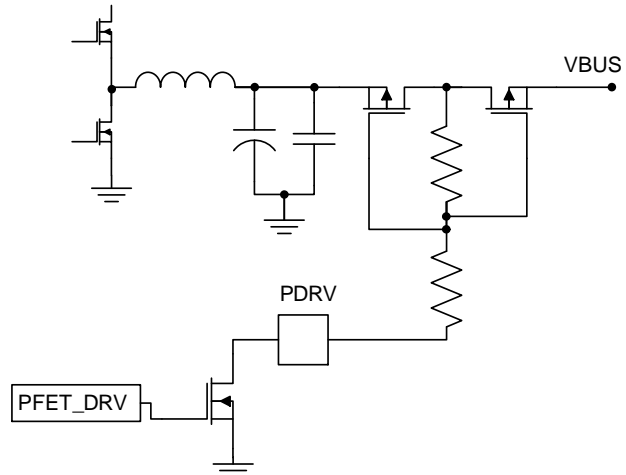


Figure 12. PFET Drive

# NCP81231

## Analog to Digital Converter

The analog to digital converter is a 7-bit A/D which can be used as an event recorder, an input voltage sampler, output voltage sampler, input current sampler, or output current sampler. The converter digitizes real time data during the sample period. The internal precision reference is used to provide the full range voltage; in the case of input voltage V1 or the feedback voltage FB (with 10:1 external resistor divider) the full range is 0 V to 25.5 V. V1 is internally divided down by 10 before it is digitized by the

ADC, thus the range of the measurement is 0 V–2.55 V, same as FB. The resolution of the V1 and FB voltage is 20 mV at the analog mux, but since the voltage is divided by 10 output voltage resolution will be 200 mV. When CS1 and CS2 are sampled, the range is 0 V–2.55 V. The resolution will be 20 mV in the CS monitoring case. The actual current can be calculated by dividing the CS1 or CS2 values with the factor of  $R_{sense} * 5mS * R_{CSx}$ , the total gain from the current input to the external current monitoring outputs.

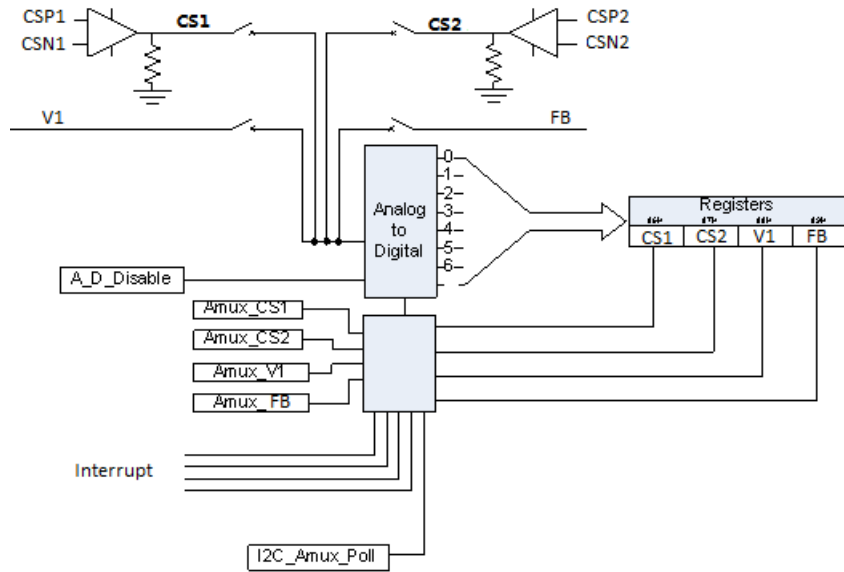


Figure 13. Analog to Digital Converter

Table 13. ADC BYTE

|      | MSB | 5  | 4  | 3  | 2  | 1  | LSB |
|------|-----|----|----|----|----|----|-----|
| DATA | D6  | D5 | D4 | D3 | D2 | D1 | D0  |

Table 14. REGISTER SETTING FOR ENABLING DESIRED ADC BEHAVIOUR

| ADC_2 | ADC_1 | ADC_0 | Description                                                   |
|-------|-------|-------|---------------------------------------------------------------|
| 0     | 0     | 0     | Sets Amux to VFB                                              |
| 0     | 0     | 1     | Sets Amux to V1                                               |
| 0     | 1     | 0     | Sets Amux to CS2                                              |
| 0     | 1     | 1     | Sets Amux to CS1                                              |
| 1     | 0     | 0     | Select all in rotating sequence (VFB, V1, CS2, CS1, VFB, ...) |



# NCP81231

## Interrupt Control

The interrupt controller continuously monitors internal interrupt sources, generating an interrupt signal when a system status change is detected. Individual bits generating interrupts will be set to 1 in the INTACK register (I<sup>2</sup>C read only registers), indicating the interrupt source. All

interrupt sources can be masked by writing 1 in register INTMSK. Masked sources will never generate an interrupt request on the INT pin. The INT pin is an open drain output. A non-masked interrupt request will result in the INT pin being driven high. Figure 14 illustrates the interrupt process.

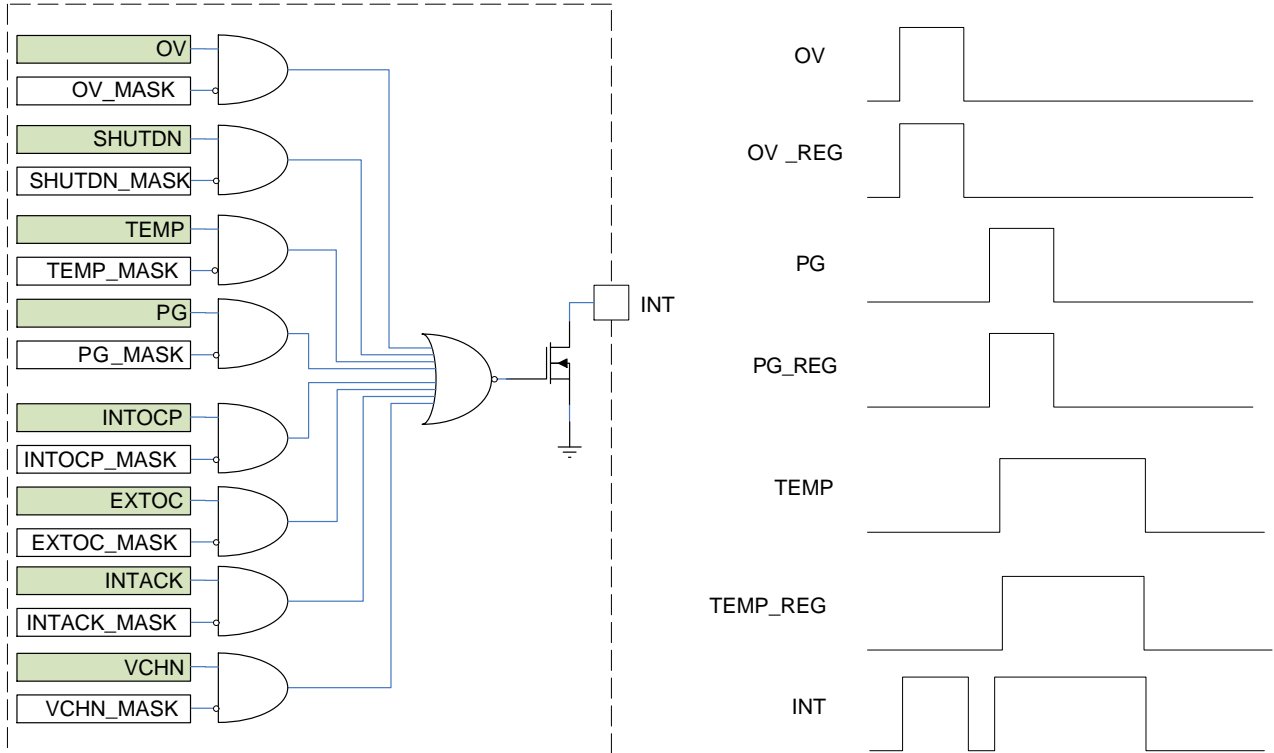


Figure 14. Interrupt Logic

Table 15. INTERPRETATION TABLE

| Interrupt Name | Description                             |
|----------------|-----------------------------------------|
| OV             | Output Over Voltage                     |
| Shutdown       | Shutdown Detection (EN=low)             |
| TEMP           | IC Thermal Trip                         |
| PG             | Power Good Trip Thresholds Exceeded     |
| INTOCP         | Internal Current Limit Trip             |
| EXTOC          | External Current Trip from CLIND        |
| VCHN           | Output Negative Voltage Change          |
| INTACK         | I <sup>2</sup> C ACK signal to the host |

## I<sup>2</sup>C Address

NCP81231 has two address selectable factory settings. The default address is set to 77h.

Table 16. I<sup>2</sup>C ADDRESS

| I <sup>2</sup> C Address | Hex  | A6 | A5 | A4 | A3 | A2 | A1 | A0 |
|--------------------------|------|----|----|----|----|----|----|----|
| ADD0 (default)           | 0x77 | 1  | 1  | 1  | 0  | 1  | 1  | 1  |
| ADD1                     | 0x76 | 1  | 1  | 1  | 0  | 1  | 1  | 0  |

# NCP81231

## I<sup>2</sup>C interface

The I<sup>2</sup>C interface can support 5 V TTL, LVTTTL, 2.5 V and 1.8 V interfaces with two precision SCL and SDA comparators with 1V thresholds shown in Figure 15. The part cannot support 5 V CMOS levels as there can be some ambiguity in voltage levels.

## I<sup>2</sup>C Compatible Interface

The NCP81231 can support a subset of I<sup>2</sup>C protocol as detailed below. The NCP81231 communicates with the

external processor by means of a serial link using a 400 kHz up to 1.2 MHz I<sup>2</sup>C two-wire interface protocol. The I<sup>2</sup>C interface provided is fully compatible with the Standard, Fast, and High-Speed I<sup>2</sup>C modes. The NCP81231 is not intended to operate as a master controller; it is under the control of the main controller (master device), which controls the clock (pin SCL) and the read or write operations through SDA. The I<sup>2</sup>C bus is an addressable interface (7-bit addressing only) featuring two Read/Write addresses.

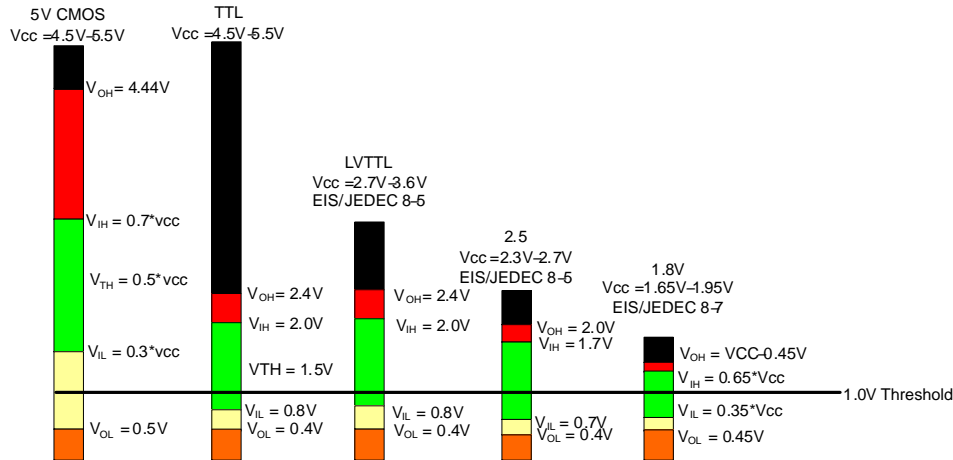


Figure 15. I<sup>2</sup>C Thresholds and Comparator Thresholds

## I<sup>2</sup>C Communication Description

The first byte transmitted is the chip address (with the LSB bit set to 1 for a Read operation, or set to 0 for a Write operation). Following the 1 or 0, the data will be:

- In case of a Write operation, the register address (@REG) pointing to the register for which it will be written is followed by the data that will be written in that location. The writing process is auto-incremental, so

the first data will be written in @REG, the contents of @REG are incremented, and the next data byte is placed in the location pointed to @REG + 1 ..., etc.

- In case of a Read operation, the NCP81231 will output the data from the last register that has been accessed by the last write operation. Like the writing process, the reading process is auto-incremental.

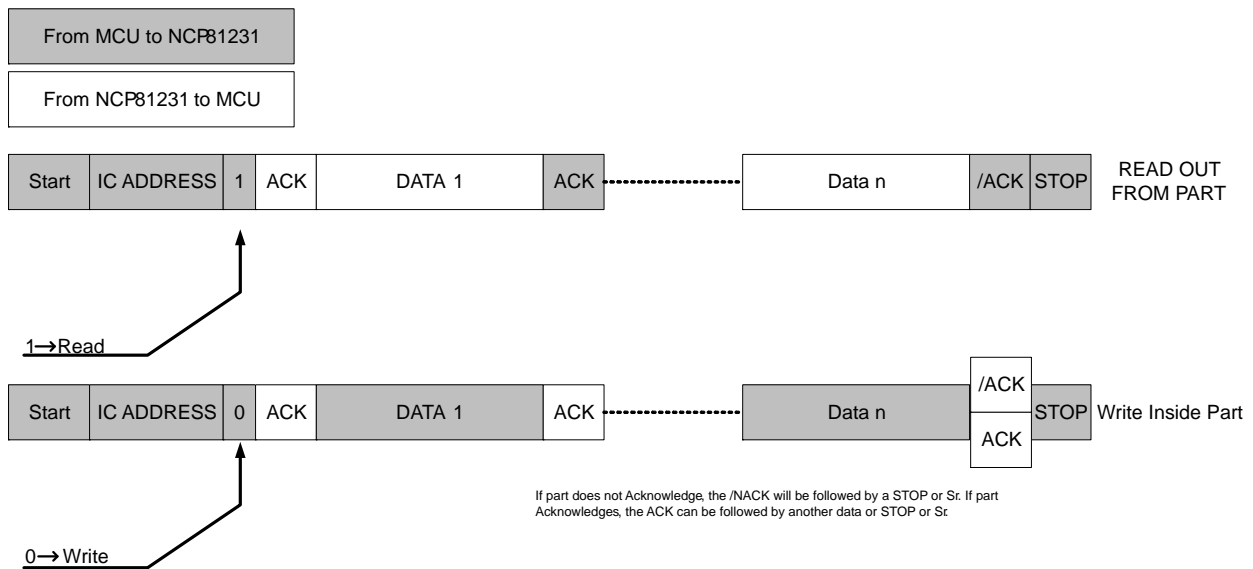


Figure 16. General Protocol Description

# NCP81231

## Read out from part

The master will first make a "Pseudo Write" transaction with no data to set the internal address register. Then, a stop

then start or a repeated start will initiate the Read transaction from the register address the initial Write transaction was pointed to:

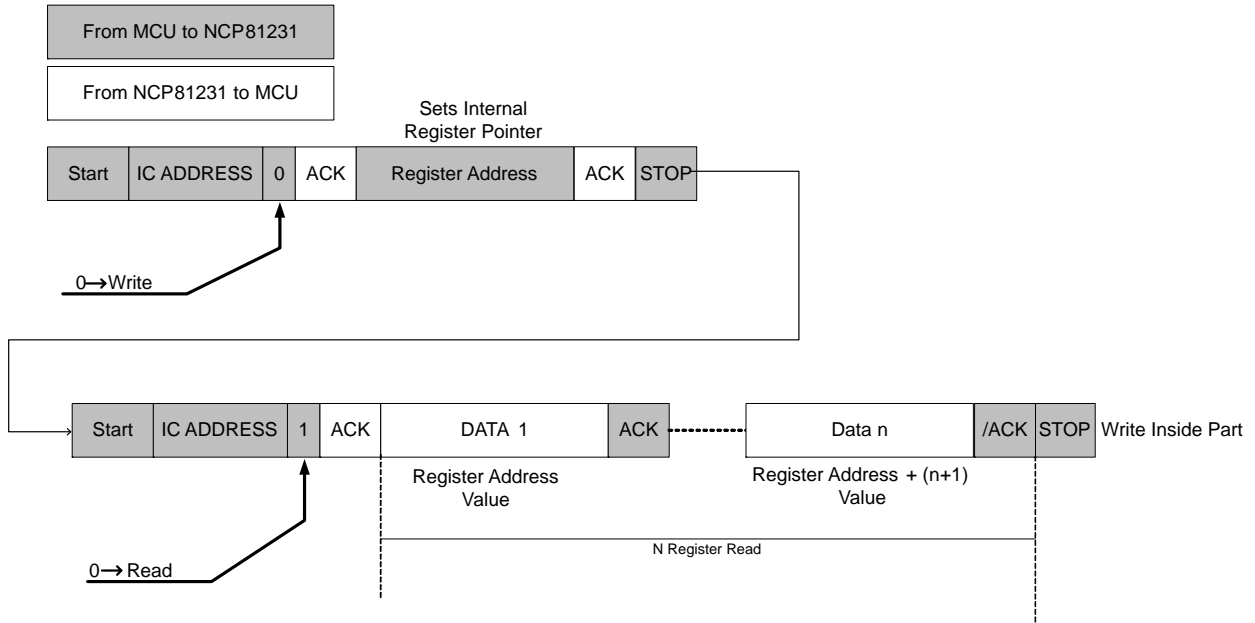


Figure 17. Read Out From Part

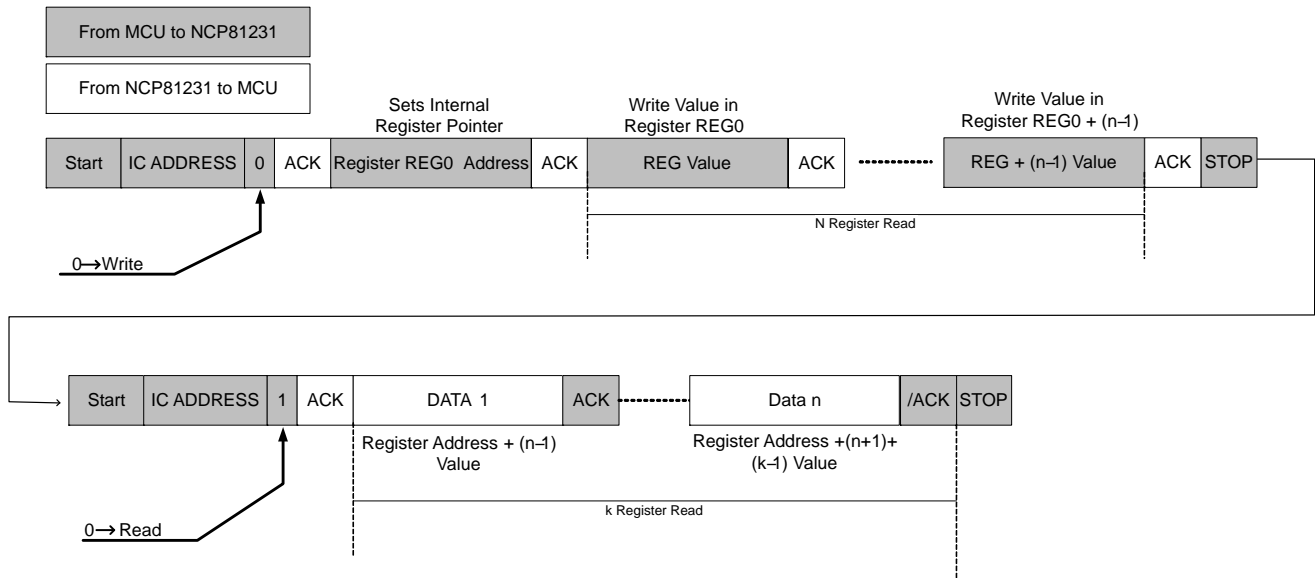


Figure 18. Write Followed by Read Transaction

# NCP81231

## Write in part

Write operation will be achieved by only one transaction. After the chip address, the MCU first data will be the internal

register desired to access, the following data will be the data written in Reg, Reg + 1, Reg + 2, ..., Reg + n.

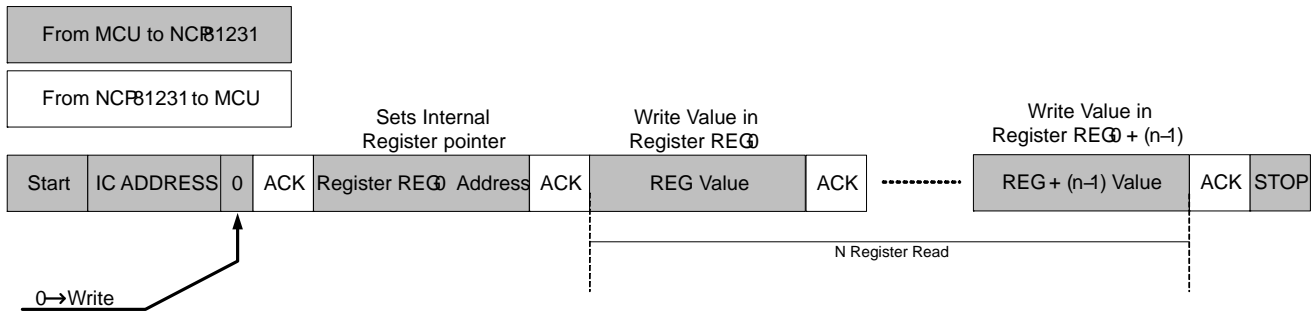
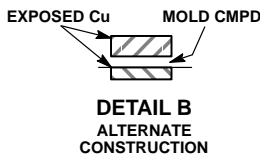
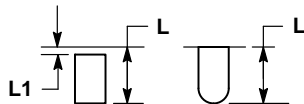
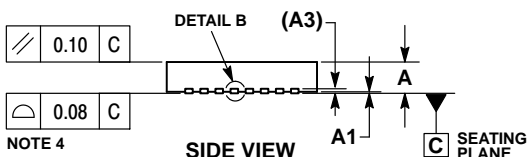
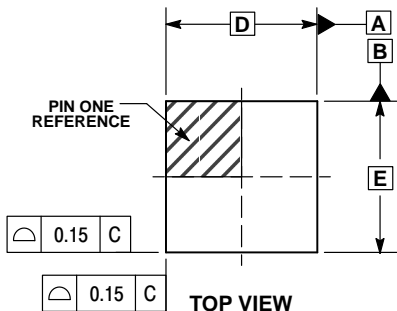


Figure 19. Write in n Registers

# NCP81231

## PACKAGE OUTLINE

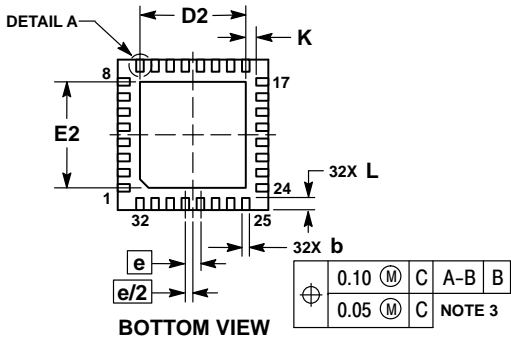
QFN32 5x5, 0.5P  
CASE 485CE  
ISSUE O



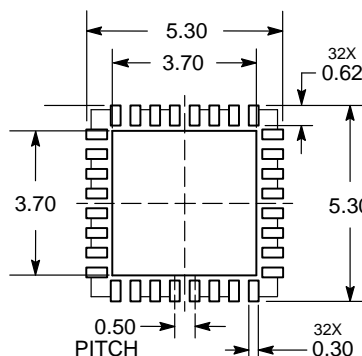
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS |      |      |
|-------------|------|------|
| DIM         | MIN  | MAX  |
| A           | 0.80 | 1.00 |
| A1          | ---  | 0.05 |
| A3          | 0.20 | REF  |
| b           | 0.20 | 0.30 |
| D           | 5.00 | BSC  |
| D2          | 3.40 | 3.60 |
| E           | 5.00 | BSC  |
| E2          | 3.40 | 3.60 |
| e           | 0.50 | BSC  |
| K           | 0.20 | ---  |
| L           | 0.30 | 0.50 |
| L1          | ---  | 0.15 |



### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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